

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32F303CCT6 STM32F303CCT6TR	S05B*422XXXY	A	998Z	22-09-2017
	Amount	UoM	Unit type	ST ECOPACK Grade
	183.48	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable; if coating is used or other bulk termination	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	7X7X1.4	48	L Bend	
Comment	Package : 58 LQFP 48 7x7x1.4 1 0110596			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH- 7th July 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration :						Mfr Item Name	S05B*422XXXY				6015601.0	4581.0
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	0.530	mg	supplier	die	Silicon (Si)	7440-21-3		0.521	mg	983019	2840
				supplier	metallization	Aluminium (Al)	7429-90-5		0.001	mg	1887	5
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	1887	5
				supplier	Passivation	Silicon Nitride	12033-89-5		0.001	mg	1887	5
				supplier	Passivation	Silicon Oxide	7631-86-9		0.006	mg	11321	33
Die Attach Epoxy_ABLEBOND 3230_H	M-011 Other inorganic materials	2.366	mg	Supplier	Metals	Silver	7440-22-4		2.131	mg	901000	11617
				Supplier	Plastics/polymers	Highly cross-linked polymer	Proprietary		0.234	mg	99000	1276
Mold Compound_EME-G631SHQ_Sur	M-011 Other inorganic materials	125.364	mg	Supplier	Plastics/polymers	Epoxy Resin A	Proprietary		2.273	mg	21000	12387
				Supplier	Plastics/polymers	Epoxy Resin B	Proprietary		2.273	mg	21000	12387
				Supplier	Plastics/polymers	Phenol Resin	Proprietary		6.061	mg	56000	33033
				Supplier	Glass	Silica(Amorphous)A	60676-86-0		101.603	mg	780450	446234
				Supplier	Glass	Silica(Amorphous)B	7631-86-9		12.481	mg	115320	68024
Wire_AG Si TYPE_MKE	Bonding Wire	0.260	mg	Supplier	Non-metals	Carbon Black	1333-86-4		0.674	mg	6230	3675
				Supplier	Metals	Silver	7440-22-4		0.250	mg	960000	1361
Plating anode_Pure Tin_Nuo Nengda	M-011 Other inorganic materials	1.078	mg	Supplier	Metals	Others	Proprietary		0.010	mg	40000	57
				Supplier	Metals	Tin	7440-31-5		1.078	mg	1000000	5878
Leadframe_C194+Ag_MITSUI	Copper & its alloys	53.878	mg	Supplier	Metals	Copper	7440-50-8		51.814	mg	961700	282404
				Supplier	Metals	Iron	7439-89-6		1.223	mg	22700	6666
				Supplier	Metals	Zinc	7440-66-6		0.081	mg	1500	440
				Supplier	Non-metals	Phosphorus	7723-14-0		0.016	mg	300	88
				Supplier	Metals	Silver	7440-22-4		0.744	mg	13800	4052
				Supplier	Metals	Zinc	7440-66-6		0.081	mg	1500	440
				Supplier	Non-metals	Phosphorus	7723-14-0		0.016	mg	300	88
				Supplier	Metals	Silver	7440-22-4		0.744	mg	13800	4052